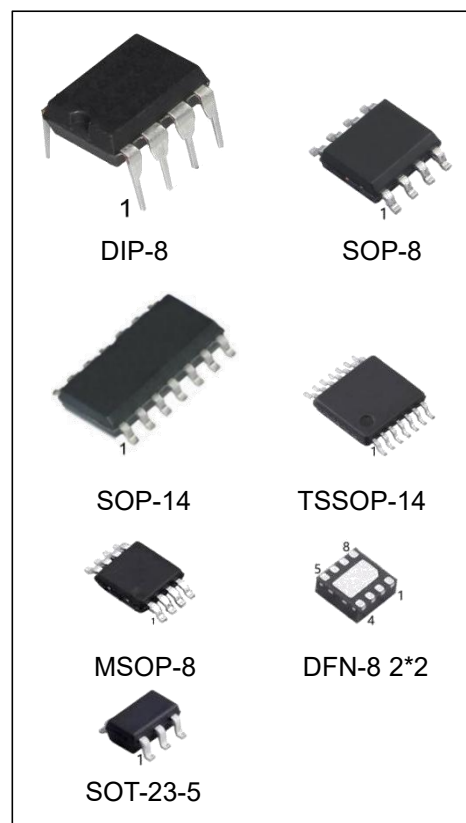


10MHz, RRIO, CMOS, Op Amps

FEATURES

- High Gain Bandwidth: 10MHz
- Excellent Slew Rate: 8.5V/Us
- Rail-To-Rail Input And Output
- Lower Offset Voltage: $\pm 0.5\text{mV}$ Max
- Input Voltage Range: -0.2V To $+5.7\text{V}$ With $V_s = 5.5\text{V}$
- Supply Range: $+2.1\text{V}$ To $+5.5\text{V}$
- Operating Range: -40°C To $+125^\circ\text{C}$
- Micro Size Packages: SOT-23-5



Ordering Information

DEVICE	Package Type	MARKING	Packing	Packing Qty
LMV721AIN	DIP-8	V721AI	TUBE	2000pcs/box
LMV721AIM/TR	SOP-8	V721AI	REEL	2500pcs/reel
LMV721AIMM/TR	MSOP-8	721AI	REEL	3000pcs/reel
LMV721AIM5/TR	SOT-23-5	721AI,A30A	REEL	3000pcs/reel
LMV721AIDQ2/TR	DFN-8 2*2	721AI	REEL	4000pcs/reel
LMV722AIN	DIP-8	V722AI	TUBE	2000pcs/box
LMV722AIM/TR	SOP-8	V722AI	REEL	2500pcs/reel
LMV722AIMM/TR	MSOP-8	722AI	REEL	3000pcs/reel
LMV722AIDQ2/TR	DFN-8 2*2	722AI	REEL	4000pcs/reel
LMV724AIM/TR	SOP-14	LMV724AI	REEL	2500pcs/reel
LMV724AIMT/TR	TSSOP-14	V724AI	REEL	2500pcs/reel

DESCRIPTION

The LMV721AI, LMV722AI, LMV724AI families of products offer low voltage operation and rail-to-rail input and output, as well as excellent speed/power consumption ratio, providing an excellent bandwidth(10MHz) and slew rate (8.5V/us). The operational amplifiers are unity gain stable and feature an ultra-low input bias current.

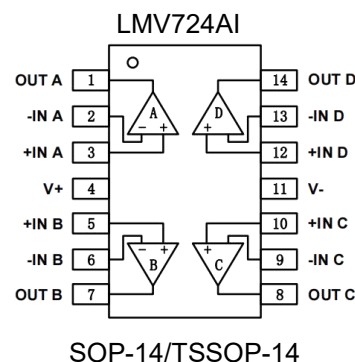
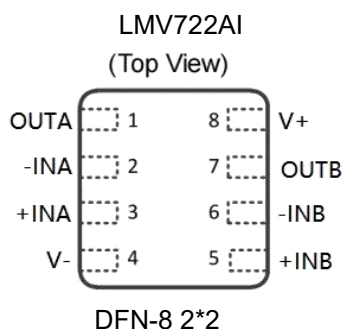
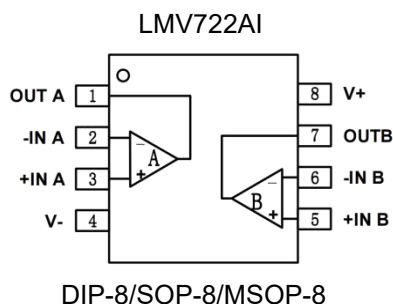
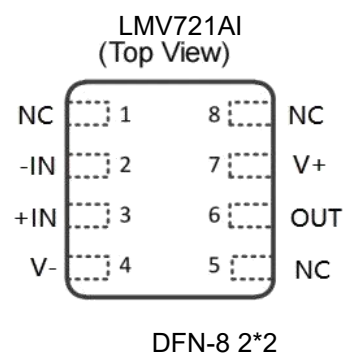
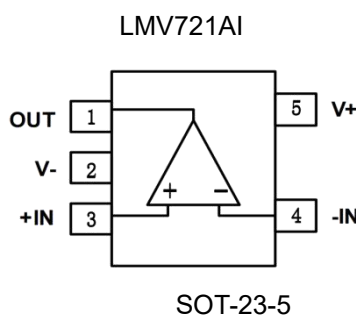
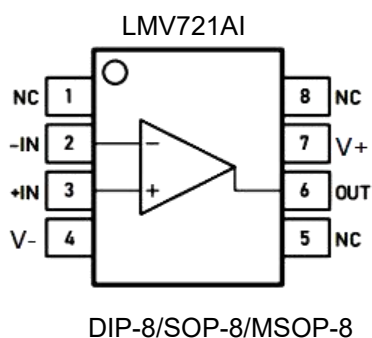
The LMV721AI, LMV722AI, LMV724AI has lower offset voltage, which is guaranteed not upper than 0.5mV at 25°C with $V_s = 5V$, $V_{CM} = V_s/2$.

The LMV721AI, LMV722AI, LMV724AI families of operational amplifiers under single supplies of 2.1V to 5.5V or dual power supplies of $\pm 1.05V$ to $\pm 2.75V$. The devices are ideal for sensor interfaces, active filters and portable applications.

APPLICATIONS

- Sensors
- Active Filters
- Test Equipment
- Driving A/D Converters
- Photodiode Amplification

Pin Configuration



Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

PARAMETER	MIN	MAX	UNIT
Supply Voltage, $V_s=(V^+) - (V^-)$		7	V
Signal Input Voltage ⁽²⁾	(V ⁻)-0.5	(V ⁺)+0.5	V
Signal Output Voltage ⁽³⁾	(V ⁻)-0.5	(V ⁺)+0.5	V
Signal Input Current	-10	+10	mA
Signal Output Current	-150	+150	mA
Maximum Junction Temperature		+150	°C
Storage Temperature Range	-65	+150	°C
Lead Temperature Range (Soldering 10 sec)		+260	°C

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

Note 2: Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current-limited to 10mA or less.

Note 3: Output terminals are diode-clamped to the power-supply rails. Output signals that can swing more than 0.5V beyond the supply rails should be current-limited to $\pm 150\text{mA}$ or less.

ESD Ratings

SYMBOL	PARAMETER		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM)	± 4500	V

Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

PARAMETER		MIN	TYP	MAX	UNIT
Supply Voltage, $V_s=(V^+) - (V^-)$	Signal-supply	2.1		5.5	V
	Dual-supply	1.05		2.75	V
Operating Temperature Range		-40	+25	+125	°C

ELECTRICAL CHARACTERISTICS

(At TA=+25°C, Vs=5V, RL=10kΩ connected to VS/2, and VOUT=VS/2, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	LMV721AI/722AI/724AI			
			MIN	TYP	MAX	UNIT
POWER SUPPLY						
Operating Voltage Range	V _S		2.1		5.5	V
Quiescent Current/Amplifier	I _Q			0.4		mA
Power-Supply Rejection Ratio	PSRR	V _s =2.5V to 5.5V,V _{CM} =(V ₋)+0.5V	75			dB
Turn-on Time	t _{ON}			12		μs
INPUT						
Input Offset Voltage	V _{OS}	V _{CM} = V _S /2, LMV721AI	-0.5	±0.2	+0.5	mV
		V _{CM} = V _S /2, LMV722AI	-0.5	±0.2	+0.5	mV
		V _{CM} = V _S /2, LMV724AI	-0.8	±0.3	+0.8	mV
Input Offset Voltage Average Drift	V _{OS} TC	TA=-40℃~+125℃		±2.6		uV/℃
Input Bias Current	I _B		-10	±1	+10	pA
Input Offset Current	I _{OS}		-10	±1	+10	pA
Common-Mode Voltage Range	V _{CM}	V _s =5.5V	-0.2		5.7	V
Common-Mode Rejection Ratio	CMRR	V _s = 5.5V, V _{CM} =-0.2V to 4V	70			dB
		V _s = 5.5V, V _{CM} =-0.2V to 5.7V	65			dB
OUTPUT						
Open-Loop Voltage Gain	A _{OL}	R _L =2KΩ, V _O =0.15V to 4.85V	86			dB
		R _L =10KΩ, V _O =0.05V to 4.95V	96			dB
Output Swing From Rail		R _L =2KΩ		50		mV
		R _L =10KΩ		10		mV
Output Current Source	I _{OUT}			140		mA
FREQUENCY RESPONSE						
Slew Rate	SR			8.5		V/μs
Gain-Bandwidth Product	GBP			10		MHz
Phase Margin	PM			62		°
Setting Time,0.1%	ts			0.5		μs
Overload Recovery Time		V _{IN} ·Gain≥V _S		3.2		μs
NOISE						
Input Voltage Noise Density	en	f = 1KHz		9.5		nV/√Hz
		f = 10KHz		6.5		nV/√Hz

TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$, $R_L = 10\text{k}\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, unless otherwise noted.

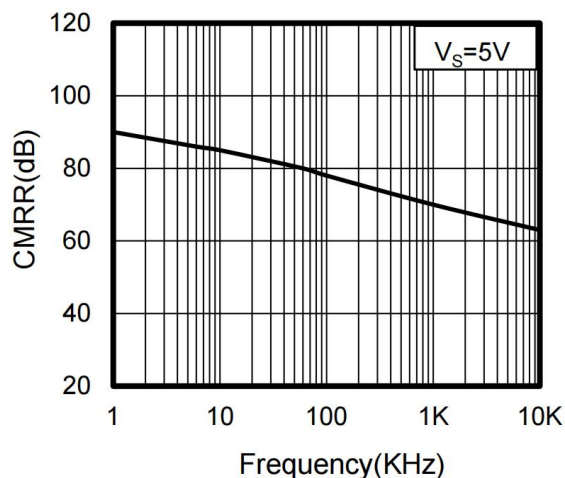


Figure 1. Common-Mode Rejection Ratio vs Frequency

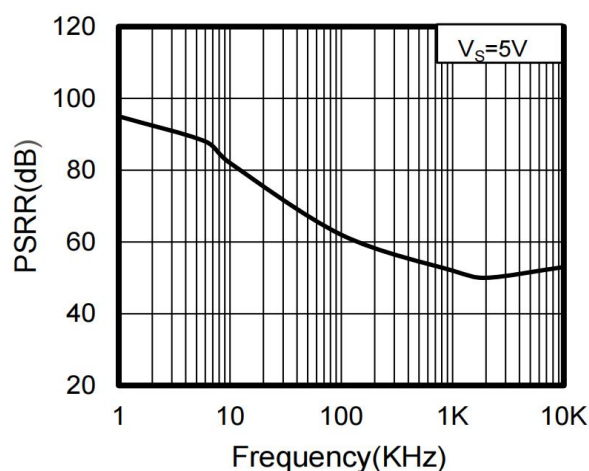


Figure 2. Power-Supply Rejection Ratio vs Frequency

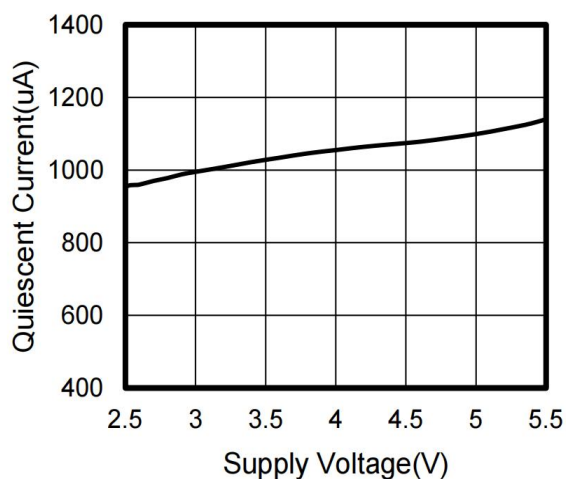


Figure 3. Quiescent Current vs Supply Voltage

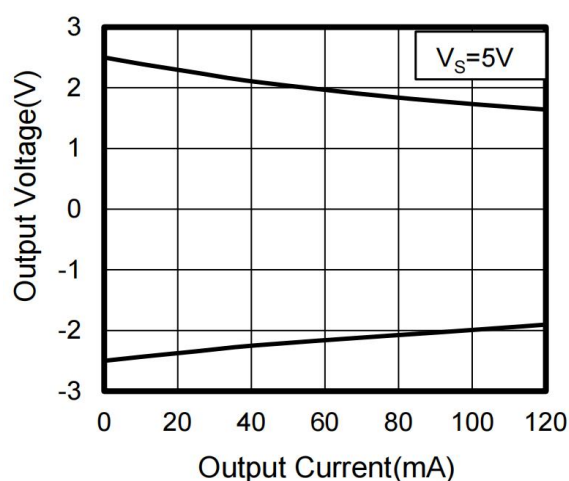


Figure 4. Output Voltage vs Output Current

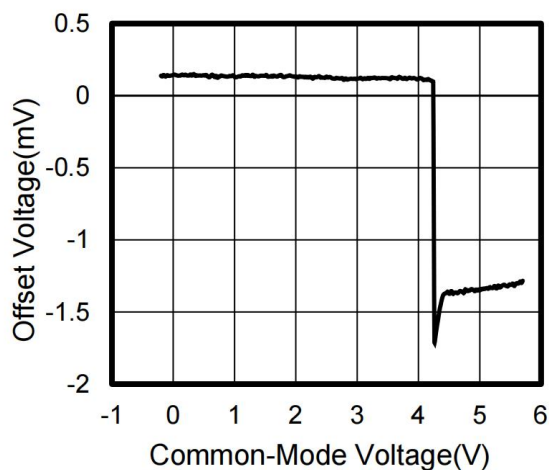


Figure 5. Offset Voltage vs Common-Mode Voltage

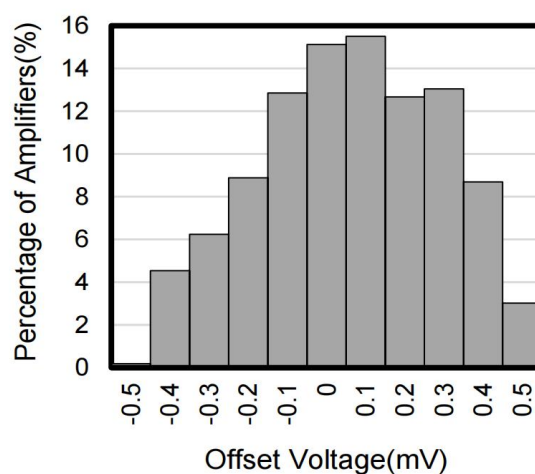


Figure 6. Offset Voltage Production Distribution

LAYOUT

Layout Guideline

Attention to good layout practices is always recommended. Keep traces short. When possible, use a PCB ground plane with surface-mount components placed as close to the device pins as possible. Place a 0.1 μ F capacitor closely across the supply pins.

These guidelines should be applied throughout the analog circuit to improve performance and provide benefits such as reducing the EMI susceptibility.

Layout Example

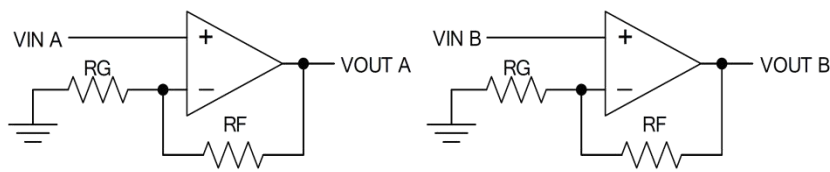


Figure 7. Schematic Representation

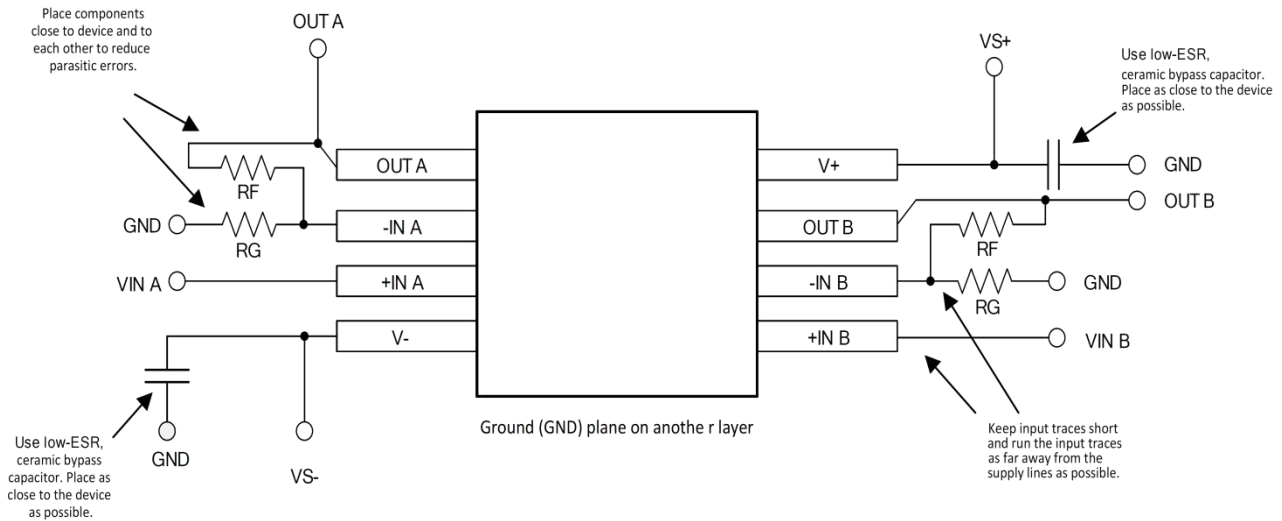
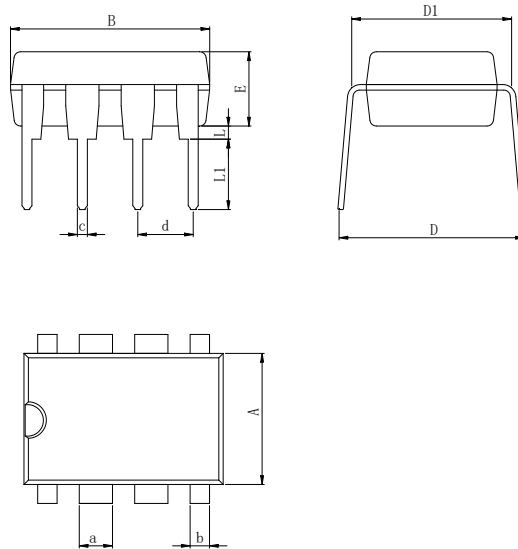


Figure 8. Layout Example

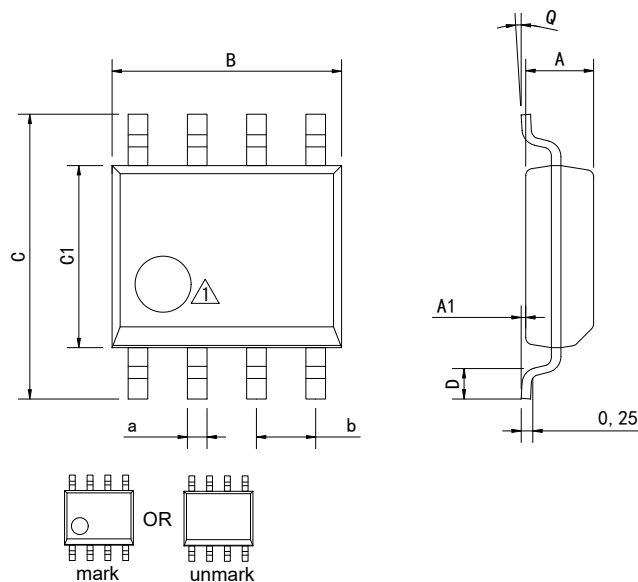
Physical Dimensions

DIP-8



Dimensions In Millimeters(DIP-8)											
Symbol:	A	B	D	D1	E	L	L1	a	b	c	d
Min:	6.10	9.00	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54 BSC
Max:	6.68	9.50	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	

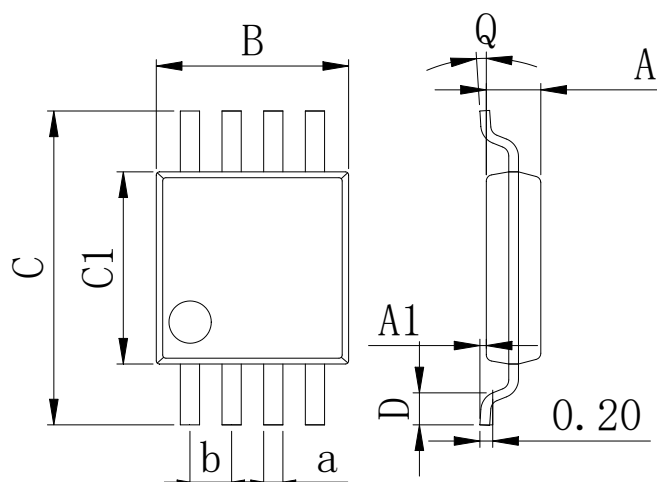
SOP-8



Dimensions In Millimeters(SOP-8)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	1.35	0.05	4.90	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.45	

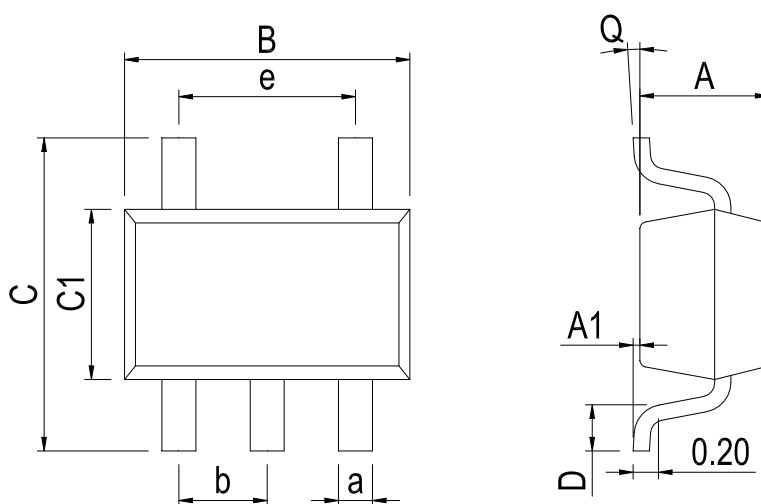
Physical Dimensions

MSOP-8



Dimensions In Millimeters(MSOP-8)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	0.80	0.05	2.90	4.75	2.90	0.35	0°	0.25	0.65 BSC
Max:	0.90	0.20	3.10	5.05	3.10	0.75	8°	0.35	

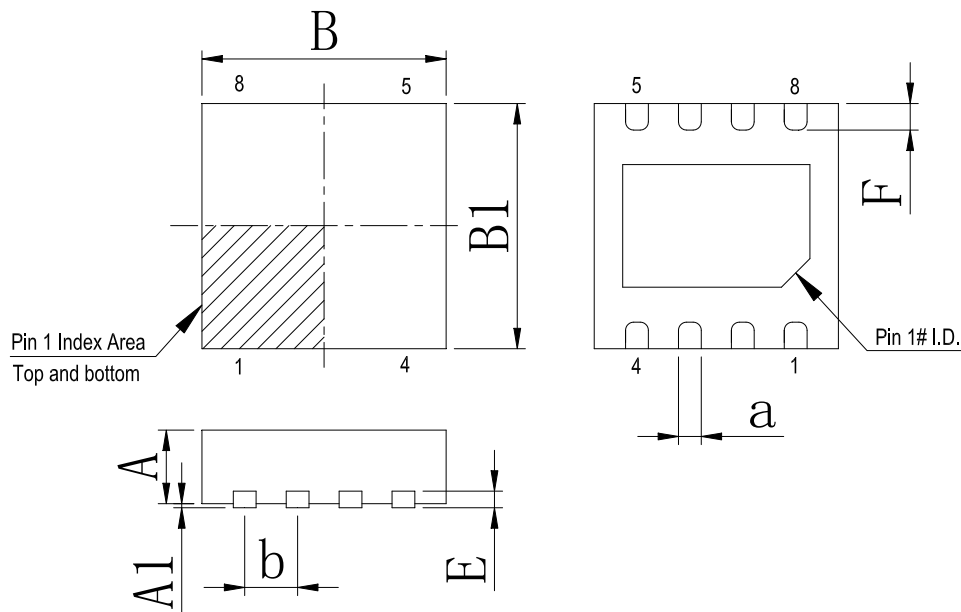
SOT-23-5



Dimensions In Millimeters(SOT-23-5)										
Symbol:	A	A1	B	C	C1	D	Q	a	b	e
Min:	1.00	0.00	2.82	2.65	1.50	0.30	0°	0.30	0.95 BSC	1.90 BSC
Max:	1.15	0.15	3.02	2.95	1.70	0.60	8°	0.50		

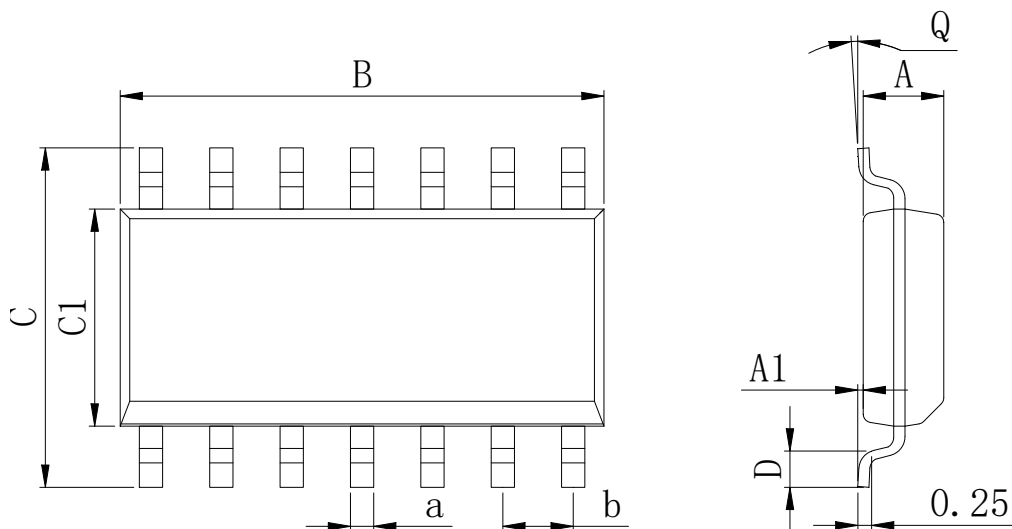
Physical Dimensions

DFN-8 2*2



Dimensions In Millimeters(DFN-8 2*2)								
Symbol:	A	A1	B	B1	E	F	a	b
Min:	0.85	0	1.90	1.90	0.15	0.25	0.18	0.50TYP
Max:	0.95	0.05	2.10	2.10	0.25	0.45	0.30	

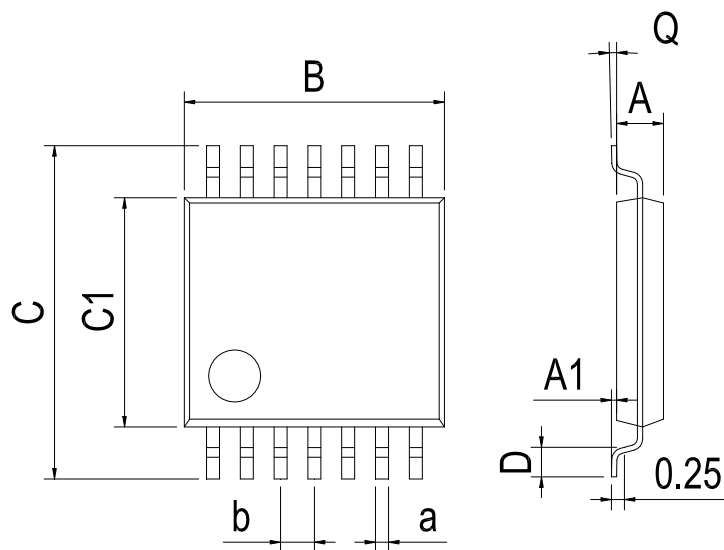
SOP-14



Dimensions In Millimeters(SOP-14)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	1.35	0.05	8.55	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	8.75	6.20	4.00	0.80	8°	0.45	

Physical Dimensions

TSSOP-14



Dimensions In Millimeters(TSSOP-14)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	0.85	0.05	4.90	6.20	4.30	0.40	0°	0.20	0.65 BSC
Max:	0.95	0.20	5.10	6.60	4.50	0.80	8°	0.25	

Revision History

REVISION NUMBER	DATE	REVISION	PAGE
V1.0	2017-11	New	1-12
V1.1	2025-6	Document Reformatting	1-12

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